













Media Sponsor: YOLE

Wednesday June 19th



Welcome to MiNaPAD – Coffee & Soft drink sponsored by 8h15

9h00 Opening by Jean-Marc YANNOU (Auditorium)

9h10 Keynote: KRÖHNERT Steffen (President & Founder of ESPAT Consulting – SEMI Europe Manager, Germany)

The Future of Semiconductor Package Manufacturing in Europe: Growing or Vanishing

	SESSION A: AI Applications	SESSION B: Attachment materials
	(Auditorium)	(Mont Blanc)
9h45	Detection and measurement of solder voids in X ray of led assembly with YOLO v8 (Yasser ALMEHIO, VALEO - France)	The Application of Low Temperature Self- Assembly Sn Based Glue (Glenn LIN, ASE group - Taiwan)
10h15	Solder paste development using AI (Melanie MATHON, INVENTEC - France)	New Bare Copper Compatible Die Attach Developments Improving Reliability and Thermal at Lower Cost (Ruud De WIT, HENKEL – The Netherlands)

10h45 - 11h15 Exhibition Opening (Exhibition Hall) / Coffee break sponsored by

SESSION C: Interconnections	SESSION D: PCB Substrates
(Auditorium)	(Mont Blanc)
Integration of III-V GaN amplifiers of an antenna in package receiver in PCB-based embedding technology	Advanced IC substrates – Challenges in the manufacturing and supply chain
(Tekfouy LIM, FRAUNHOFER IZM - Germany)	(Roland STEIM, DYCONEX - Switzerland)
Alternative approach to Die-to-Wafer bonding utilizing	XXXXX
atmospheric plasma cleaning	(xxxx)
(Daniel PASCUAL, ONTOS - USA)	
	High Density Organic Substrates for Chiplet and High Frequency Application
Clips bonding using re-metallization techniques	(Lars BOTTCHER, FRAUNHOFER IZM -
(Wilfrid AKLAMAVO, SERMA Microelectronics -	Germany)

TELEDYNE 62V | Semiconductors

12h45 - 13h45 Lunch (Exhibition Hall) sponsored by

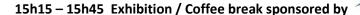
11h15

11h45

12h15

France)

	SESSION E: Process Optimization 1 (Auditorium)	SESSION F: Reliability 1 (Mont Blanc)
13h45	An innovative deposition technology for conductive & dielectric materials; Multi materials, Multilayers, Contactless High-	Robustness and environmental impact of under bump metallization for wafer level balling (Arnaud GARNIER, CEA LETI - France)
	Resolution High-Speed Deposition (Stéphane ETIENNE, I-O-TECH, Israel)	(Amada GARRIER, CEA LETT-Trance)
14h15	SWEET (Side Wall Exquisite Enveloping Technology) to protect WLSCP (Shih Chieh TANG, ASE group)	SACN doped Mn solder balls oxidation study for BGA's reliability performance (Stelliane GROLIER LEE, STMicroelectronics - France)
14h45	Post plasma dicing clean in Batch spray equipment with sulfuric ozone mixtures (Moritz MITTERMAYR, SICONNEX - Austria)	Experimental study of interfacial adhesion of passivation/resin with shear test: first learnings (Marie DUGOR DENTONE, STMicroelectronics - France)





SESSION G: Dicing / Picking (Auditorium)

15h45 Plasma Singulation of Single Power Diodes Bonded by

Intermetallic Eutectic Technique

(Sabrina ROZA-ORTIZ, PLASMATHERM - USA)

16h15 Latest approaches of dicing and grinding for

semiconductor device manufacturing

(Benjamin BERNARD, DISCO - Germany)

16h45 Industrial Approach for Plasma Dicing: Advances and

Challenges

(Lucile BROUSSOUS, STMicroelectronics – France)

17h15 Precision plasma dicing of wafers

(Leslie LEA, PLASMATHERM - USA)

SESSION H: Flip Chip Process
(Mont Blanc)

Development of a dipping process for silver

sintered flip chip interconnexion

(Céline FEAUTRIER, CEA LETI - France)

Flux less soldering in activated hydrogen

atmosphere

(Jeff BLAIR, SIKAMA - USA)

Displacement mechanisms of polymer

adhesives used in the flip chip interconnected

structures

(Nacer AITMANI, CEA LETI - France)

Innovative interconnect material for semiconductor assembly and advanced

packaging

(Sze Pei LIM, INDIUM – United Kingdom)

17h45 – 18h30 Exhibition Hall

Social Event:

Bus transportation: meeting point WTC Hall (rue de la Frise)

Departure Time: 18h45

Location: Domaine de Charmeil (154 Impasse Grande Grange 38210 St Quentin sur Isère)



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Thursday June 20th

8h30 - Opening exhibition and conferences

9h10 Keynote: Thomas ROMONT (Senior PCB Expert, IFTEC - France)

IPC Designers Council France - What are our common Challenges for Future?

Session J: Power Management (Auditorium)

Session K: Characterization (Mont Blanc) Dual blocks QFN warpage characterization

09h45 **Understanding Criticality of Thermal**

Performance in Thermal Interface Material for

Automotive Applications

(Nicolas RIEM, HENKEL - The Netherlands)

(Federico LEONE, STMicroelectronics - Italy)

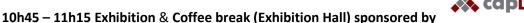
10h15 Packaging and reliability challenges for

Innovative Automative Grade current sensors

(Alastair ATTARD, UTAC - Switzerland)

Die bending methodology to explore Deep Trench Isolation crack initiation risk in Backside **Imager Sensors**

(Caroline MOUTIN, STMicroelectronics -France)





Session L: Process Optimization 2 (Auditorium)

In Situ characterization of plasma species for

process optimization and improvement (Djamila CHOU, STMicroelectronics - France) **Session M: Sustainability** (Mont Blanc)

Fabrication of low density3D PCB using piezo-

ink jet and 6 axis robots

(Davide BENNEVENTI, INPG - France)

11h45 Direct silicon wafer bonding outside cleanroom

conditions

11h15

13h45

14h15

(Chrysoula Nikoleta MANOLAKI, DTU Electro -

Denmark)

High Precision Capillary Printing (HPCAP) and its

sustainable value in electronics

(Julien VITIELLO, HUMMINK - France)

12h15 Two steps collective bonding, from dicing-tape

to device over 10000 UPH

(Aurélien GRIFFART, SET - France)

Sustainable and circular PCB using

biobased/biodegradable substrates and metals

bioleaching

(Vincent GRENNERAT, INPG CROMA - France)

THE NEW VALUE FRONTIER

12h45 - 13h45 Lunch & Exhibition (Exhibition Hall) sponsored by

Session N: Molding process (Auditorium)

Environment-friendly Epoxy Molding Compounds for Semiconductors and

Automotive

(Takahiro WATANABE, Sumitomo Bakelite Co.

Ltd - Japan)

Session O: Reliability 2 (Mont Blanc)

Enhanced Board Level Reliability Method for High Performance Automotive BGA Packages (Nohora CAICEDO, STMicroelectronics -

France)

Advanced Mold Design Solutions to Counteract Surface Discoloration in Flip Chip Encapsulation

(Roberto DOSSI, ASE group - Taiwan)

The Effects of Voids on Solder Joint Reliability in First Level Interconnect

(Sze Pei LIM, INDIUM – United Kingdom)

Session P: Interposer 2.5D TSV 3D (Auditorium)

14h55 Design and verification of a 2.5 Heterogeneous Integration Platform

(Jeroen SCHELKENS & Dimitrios TSIAKOS, IMEC - Belgium)

15h25 Unlocking the Trends and Challenges in Advanced 3D Heterogeneous Integration

Manufacturing

(Rayane MAZARI, YOLE Group - France)

15h50 Hermetically sealed glass interposer platform for photonics integrated circuits

(Kevin KROEHNERT, FRAUNHOFER IZM - Germany)

16h15 Si Based integrated passive devices for Sub 6G SiP

(Mark AZZOPARDI, JCET group - Switzerland)

16h45 Closing MiNaPAD 2024 Conference by Jean-Marc YANNOU (Auditorium)

Address:



World Trade Centre Grenoble

5-7 place Robert Schuman 38025 Grenoble

http://www.congres-wtcgrenoble.com/

List of Exhibitors

Booth number	Company		
1	IMAPS - PACK4EU		
2	ASE		
3	EMPC - IEEE		
4	NANOTEC		
5	ONTOS		
6	CDS - NAMICS		
7	MICROLIGHT 3D		
8	GS SWISS PCB		
9	ELEMCA		
10	METRONELEC		
11	MICON GLOBAL		
12	KYOCERA		
13	SET		
14	NITERRA		
15	ACCELONIX		
16	AEMTEC		
17	EGIDE		
18	MST		
19	TAIPRO		
20	ISP SYSTEM		
21	BT ELECTRONICS		
22	TELEDYNE E2V		
23	HYBRID		
24	FINETECH		
25	MICROWORLD		
26	SERMA Microelectronics		
27	ELECTRON MEC		
28	HEF Groupe		
29	CEA		
30	SYNERGY CAD		
31	PROTAVIC		
32	DISCO		
33	YOLE		
34	CTS		
34	UIS		

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FEES:								
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IMAPS Member IMAPS 2024 and IEEE 2024 Membership 390 € VAT excl. Please confirm your attendance to social event								
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Condition of payment: No refund in case of cancellation VAT not required for non-French Companies by chèque to IMAPS (France only) Payment by bank transfer Registration and Payment on line https://event.imapsfrance.org Purchase order (PO)								

IMAPS BANK REFERENCES

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